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**ABSTRACT OF THE DISCLOSURE**

An integrated circuit having at least one micromechanical element thereon is described comprising a support substrate, a sensor element electrically connected to a logic circuit, and the logic circuit electrically connected to a semiconductor visual display element.

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The integrated circuit may be manufactured by a process which comprises:

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a) providing a support substrate,

b) forming at least two elements selected from the group consisting of a micromechanical sensor element, a logic circuit and a semiconductor visual display element on said support, and

c) manufacturing a third element on said support substrate, said third element selected from the group consisting of a micromechanical sensor element, a logic circuit and a semiconductor visual display element which was not provided in step b).

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In one embodiment of the process of manufacture, all three of the at least three elements are constructed on the support itself, preferably by microlithographic processes.

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